Advance Information

Surface Mount Schottky Power Rectifier

SMB Power Surface Mount Package

MBRS2040LT3

SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES 40 VOLTS

CASE 403A–03 SMB

. . . employing the Schottky Barrier principle in a metal–to–silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

- Compact Package with J–Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over–Voltage Protection
- Low Forward Voltage Drop

Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL94, VO at 1/8″
- Weight: 95 mg (approximately)
- Maximum Temperature of 260°C / 10 Seconds for Soldering
- Polarity: Notch in Plastic Body Indicates Cathode Lead
- Available in 12 mm Tape, 2500 Units per 13 inch Reel, Add “T3” Suffix to Part Number
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Marking: BKJL

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	40	V
Average Rectified Forward Current (At Rated V_R, T_C = 103°C)	I_O	2.0	A
Peak Repetitive Forward Current (At Rated V_R, Square Wave, 20 kHz, T_C = 104°C)	I_{FRM}	4.0	A
Non–Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz)	I_{FSM}	70	A
Storage / Operating Case Temperature	T_{stg}, T_C	–55 to 150	°C
Operating Junction Temperature	T_J	–55 to 125	°C
Voltage Rate of Change (Rated V_R, T_J = 25°C)	dv/dt	10,000	V/μs

THERMAL CHARACTERISTICS

Thermal Resistance – Junction–to–Lead (2) Thermal Resistance – Junction–to–Ambient (3)	R_{tjl} R_{tja}	22.5 78	°C/W

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (1), See Figure 2	V_F	**T_J = 25°C**	**T_J = 125°C**	V
(I_F = 2 A) (I_F = 4 A)		0.43 0.50	0.34 0.45	
Maximum Instantaneous Reverse Current, See Figure 4	I_R	**T_J = 25°C**	**T_J = 100°C**	mA
(V_R = 40 V) (V_R = 20 V)		0.80 0.10	20 6.0	

(1) Pulse Test: Pulse Width ≤ 250 μs, Duty Cycle ≤ 2.0%.

(2) Minimum pad size (0.108 X 0.085 inch) for each lead on FR4 board.

(3) 1 inch square pad size (1 X 0.5 inch for each lead) on FR4 board.

This document contains information on a new product. Specifications and information herein are subject to change without notice.

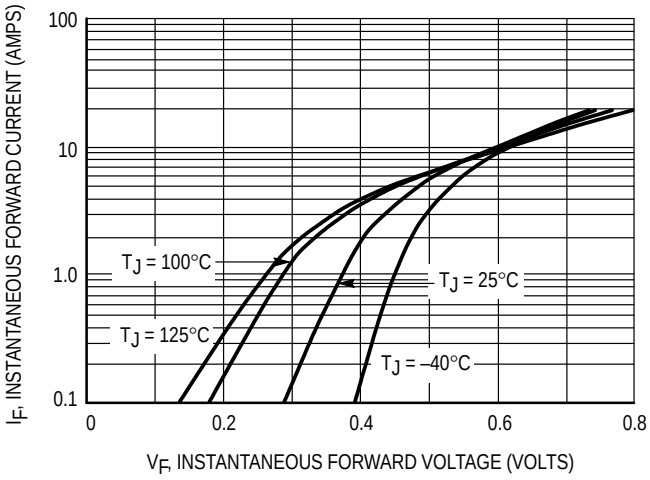


Figure 1. Typical Forward Voltage

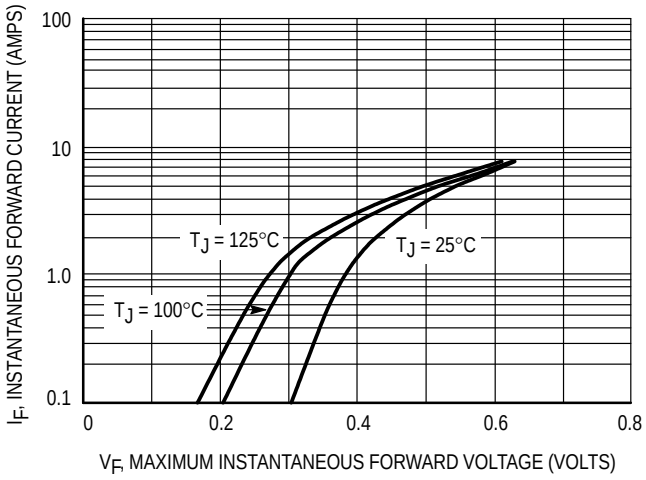


Figure 2. Maximum Forward Voltage

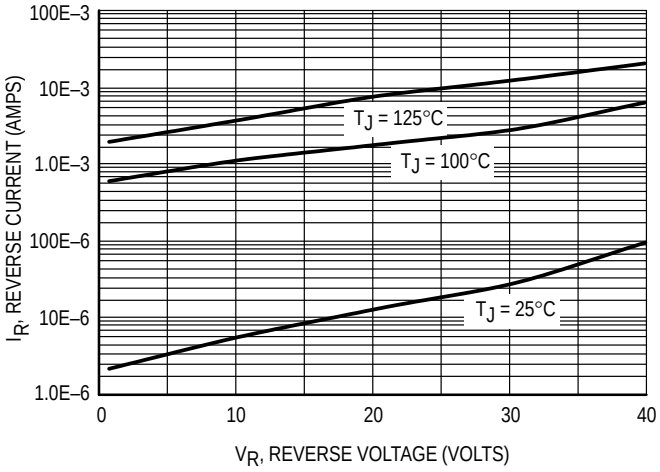


Figure 3. Typical Reverse Current

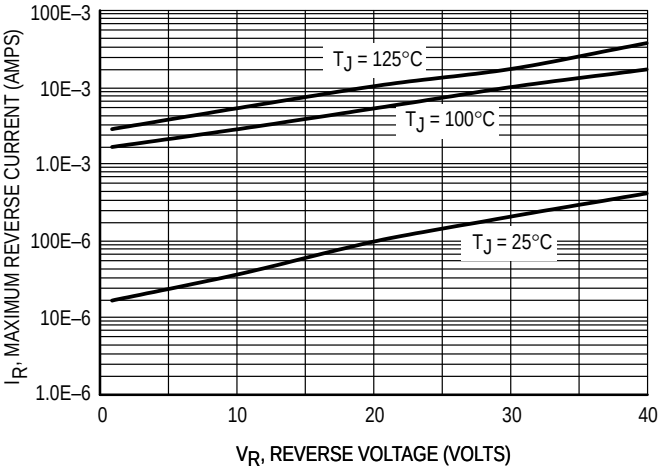


Figure 4. Maximum Reverse Current

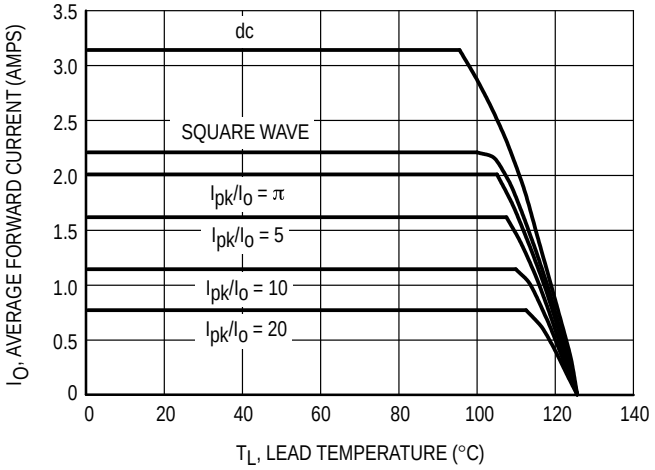


Figure 5. Current Derating

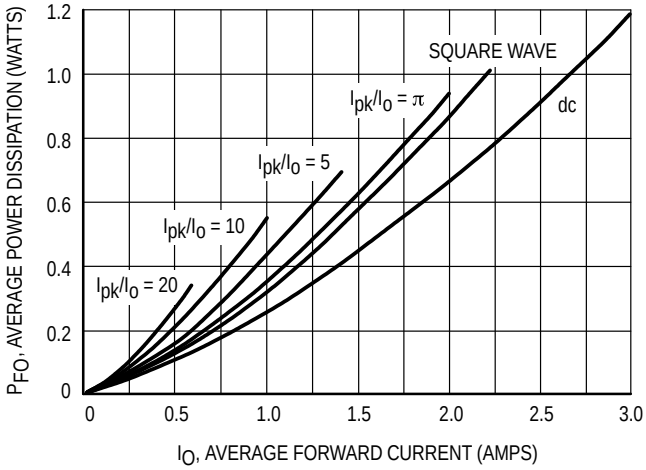


Figure 6. Forward Power Dissipation

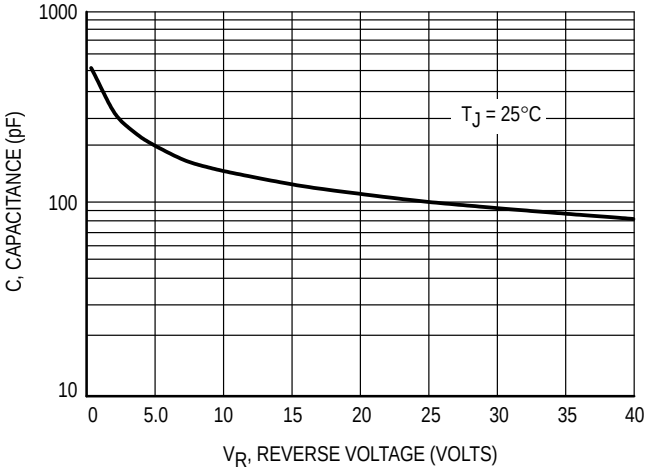


Figure 7. Capacitance

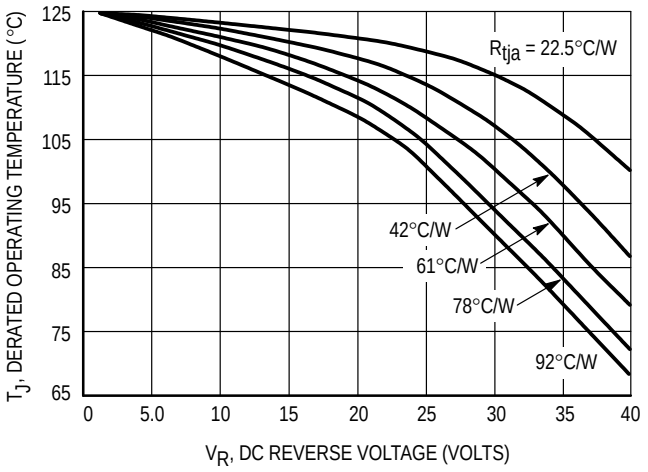


Figure 8. Typical Operating Temperature Derating*

* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating T_J may be calculated from the equation: $T_J = T_{Jmax} - r(t)(Pf + Pr)$ where
r(t) = thermal impedance under given conditions,
Pf = forward power dissipation, and
Pr = reverse power dissipation
This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)Pr$, where r(t) = Rthja. For other power applications further calculations must be performed.

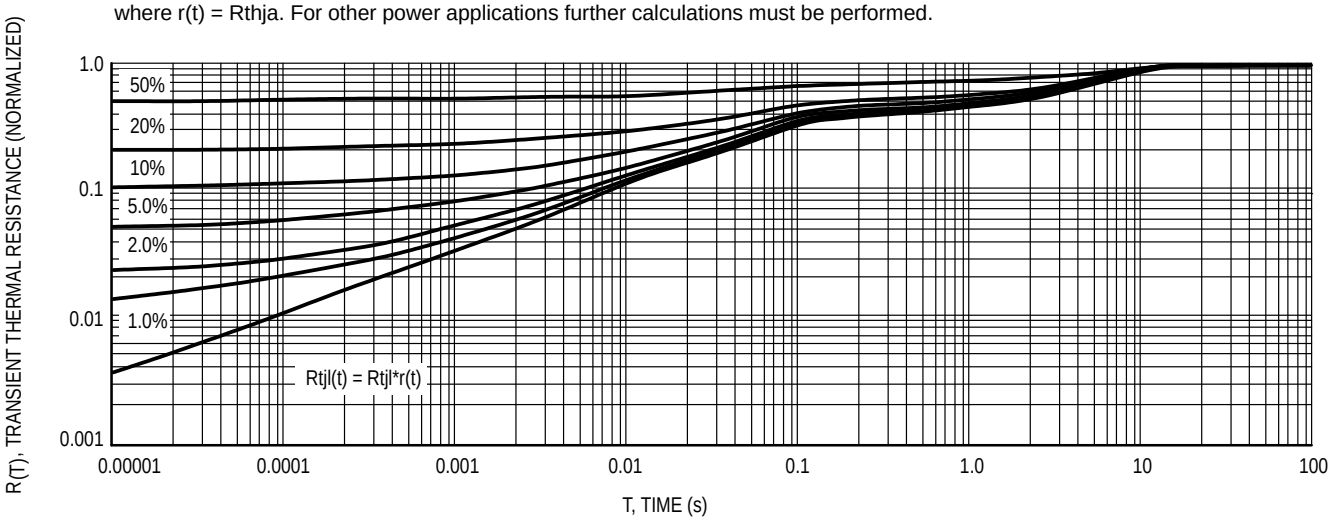


Figure 9. Thermal Response Junction to Lead

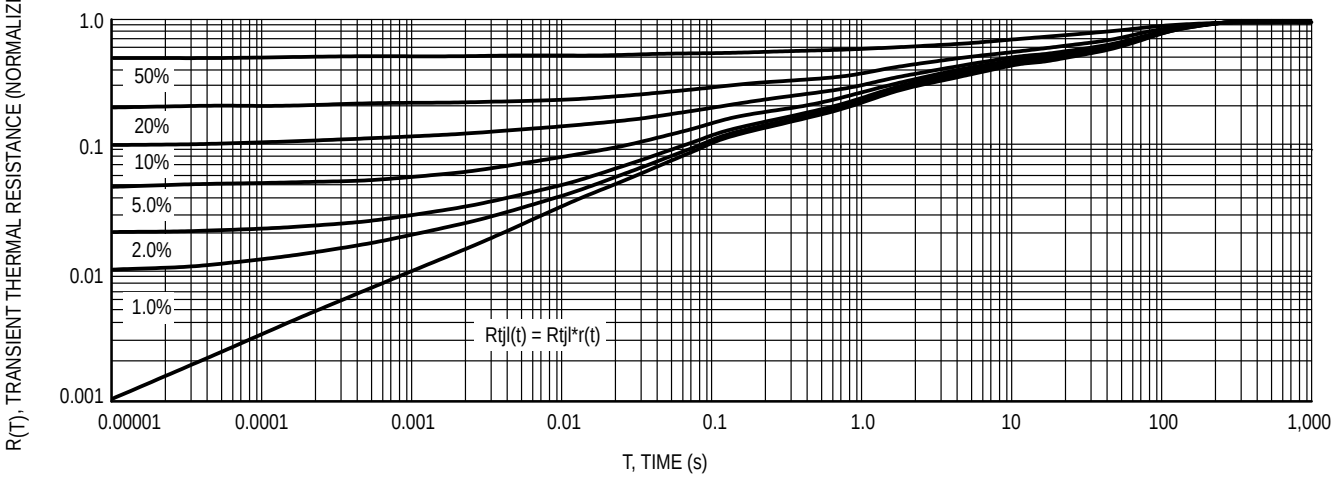
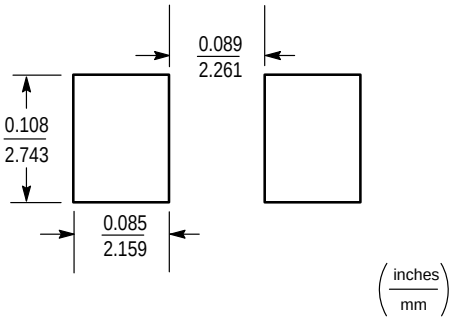
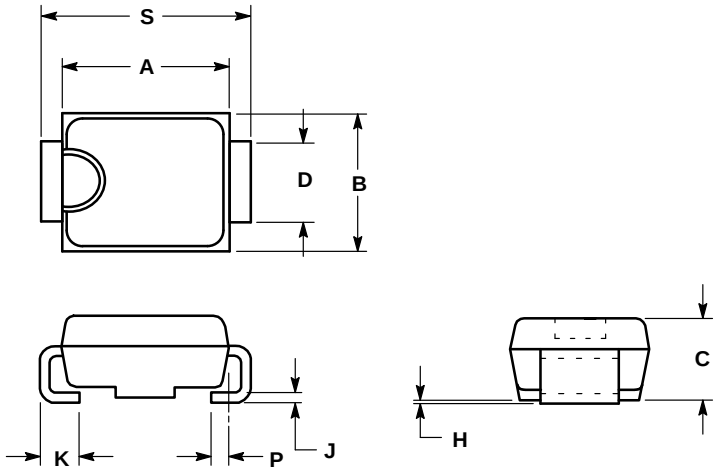


Figure 10. Thermal Response Junction to Ambient



SMB

PACKAGE DIMENSIONS



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.160	0.180	4.06	4.57
B	0.130	0.150	3.30	3.81
C	0.075	0.095	1.90	2.41
D	0.077	0.083	1.96	2.11
H	0.0020	0.0060	0.051	0.152
J	0.006	0.012	0.15	0.30
K	0.030	0.050	0.76	1.27
P	0.020 REF		0.51 REF	
S	0.205	0.220	5.21	5.59

CASE 403A–03
ISSUE B

How to reach us:
USA / EUROPE / Locations Not Listed: Motorola Literature Distribution; P.O. Box 5405, Denver, Colorado 80217. 303–675–2140 or 1–800–441–2447

Mfax™: RMFAX0@email.sps.mot.com – TOUCHTONE 602–244–6609
INTERNET: http://Design–NET.com

JAPAN: Nippon Motorola Ltd.; Tatsumi–SPD–JLDC, 6F Seibu–Butsuryu–Center, 3–14–2 Tatsumi Koto–Ku, Tokyo 135, Japan. 81–3–3521–8315

ASIA / PACIFIC: Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park, 51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852–26629298